

General Description

The Sanrise SRC65R100B is a high voltage power MOSFET, fabricated using advanced super junction technology. The resulting device has extremely low on resistance, low gate charge and fast switching time, making it especially suitable for applications which require superior power density and outstanding efficiency.

The SRC65R100B break down voltage is 650V and it has a high rugged avalanche characteristics.

The SRC65R100B is available in TO-220F, TO-263-2, TO-220C and TO-247 packages.

Features

- Ultra Low $R_{DS(ON)} = 100m\Omega @ V_{GS} = 10V$.
- Ultra Low Gate Charge, $Q_g = 86nC$ typ.
- Intrinsic Fast-Recovery Body Diode
- Fast switching capability
- Robust design with better EAS performance
- Non-automotive Qualified

Application

- AC/DC Power Supply
- EV Charger
- PC / Server / Telecom

Ordering Information

SRC65R100B□□-□		
Circuit Type	_____	E: Lead Free
Package	_____	G: Green
TF: TO-220F		Blank: Tube
T: TO-247		TR: Tape & Reel
S2: TO-263-2		

Symbol

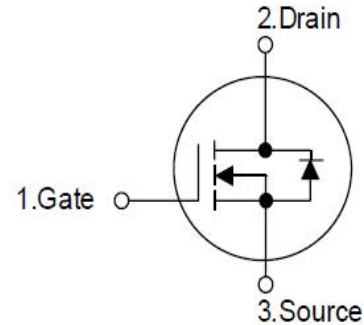


Figure 1 Symbol of SRC65R100B

Package Type

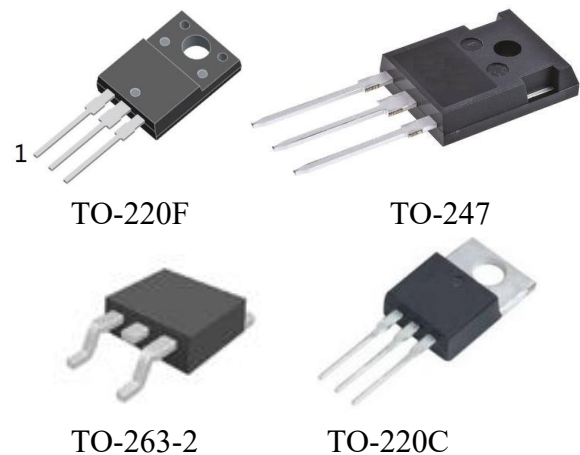


Figure 2 Package Types of SRC65R100B

Package	Part Number		Marking ID		Packing Type
	Lead Free	Green	Lead Free	Green	
TO-220F	SRC65R100BTF-E	SRC65R100BTF-G	SRC65R100BTFE	SRC65R100BTFG	Tube
TO-247	SRC65R100BT-E	SRC65R100BT-G	SRC65R100BTE	SRC65R100BTG	Tube
TO-263-2	SRC65R100BS2TR-E	SRC65R100BS2TR-G	SRC65R100BS2E	SRC65R100BS2G	Tape & Reel
TO-220C	SRC65R100BTC-E	SRC65R100BTC-G	SRC65R100BTCE	SRC65R100BTCG	Tube

Absolute Maximum Ratings^{Note 1}

Parameter		Symbol	Rating	Unit
Drain-Source Voltage		V_{DS}	650	V
Gate-Source Voltage (static)		V_{GS}	±20	V
Gate-Source Voltage (dynamic), AC ($f > 1$ Hz)			±30	V
Continuous Drain Current	$T_C = 25^\circ\text{C}$	I_D	36.9	A
	$T_C = 125^\circ\text{C}$		16.5	
Pulsed Drain Current (Note 2)		I_{DM}	110.7	A
Avalanche Energy, Single Pulse (Note 3)		E_{AS}	100	mJ
Avalanche Energy, Repetitive (Note 2)		E_{AR}	0.6	mJ
Avalanche Current, Repetitive (Note 2)		I_{AR}	4.5	A
Continuous Diode Forward Current		I_S	36.9	A
Diode Pulse Current		$I_{S,PULSE}$	110.7	A
MOSFET dv/dt Ruggedness, $V_{DS} \leq 480\text{V}$		dv/dt	80	V/ns
Reverse Diode dv/dt , $V_{DS} \leq 480\text{V}$, $I_{SD} \leq I_D$		dv/dt	50	V/ns
Power Dissipation (TO-220F)		P_{tot}	35.7	W
Power Dissipation (TO-220C, TO-263-2, TO-247)		P_{tot}	291	W
Operating Junction Temperature		T_J	150	$^\circ\text{C}$
Storage Temperature		T_{STG}	-55 to 150	$^\circ\text{C}$
Lead Temperature (Soldering, 10 sec)		T_{LEAD}	260	$^\circ\text{C}$

Note:

1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
2. Repetitive Rating: Pulse width limited by maximum junction temperature
3. $I_{AS} = 4.5\text{A}$, $V_{DD} = 60\text{V}$, $R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$

Thermal characteristics

Parameter		Symbol	Min	Typ	Max	Unit
Thermal resistance, Junction-to-Case	TO-220F	R_{thJC}			3.5	$^\circ\text{C} / \text{W}$
	TO-220C				0.43	
	TO-263-2				0.43	
	TO-247				0.43	
Thermal resistance, Junction-to-Ambient	TO-220F	R_{thJA}			70	$^\circ\text{C} / \text{W}$
	TO-220C				58	
	TO-263-2				58	
	TO-247				58	

Electrical Characteristics

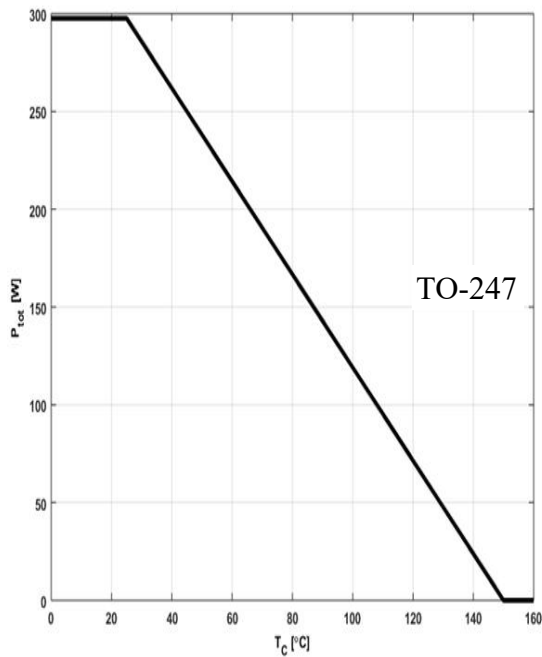
$T_J = 25^\circ\text{C}$, unless otherwise specified.

Parameter		Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics							
Drain-Source Breakdown Voltage		BV _{DSS}	V _{GS} =0V, I _D =250uA	650			V
Zero Gate Voltage Drain Current		I _{DSS}	V _{DS} =650V, V _{GS} =0V			10	uA
Gate-Body Leakage Current	Forward	I _{GSSF}	V _{GS} =20V, V _{DS} =0V			100	nA
	Reverse	I _{GSSR}	V _{GS} =-20V, V _{DS} =0V			-100	nA
Gate Threshold Voltage		V _{GS(TH)}	V _{DS} =V _{GS} , I _D =800uA	3.0	4.0	5.0	V
Static Drain-Source On-Resistance		R _{DS(ON)}	V _{GS} =10V, I _D =18A		82	100	mΩ
Gate Resistance		R _G	f=1MHz, Open Drain		0.7		Ω
Dynamic Characteristics							
Input Capacitance		C _{ISS}	V _{DS} =25V, V _{GS} =0V, f=1MHz		3333		pF
Output Capacitance		C _{OSS}			3466		
Reverse Transfer Capacitance		C _{RSS}			46.9		
Effective output capacitance, energy related ^{NOTE5}		C _{O(er)}	V _{GS} =0V, V _{DS} =0...400V		98.2		pF
Effective output capacitance, time related ^{NOTE6}		C _{O(tr)}			601		
Turn-on Delay Time		t _{d(on)}	V _{DD} =400V, I _D =18A R _G =1.8Ω, V _{GS} =10V		24		ns
Rise Time		t _r			38		
Turn-off Delay Time		t _{d(off)}			48		
Fall Time		t _f			10		
Gate Charge Characteristics							
Gate to Source Charge		Q _{gs}	V _{DD} =480V, I _D =18A V _{GS} =0 to 10V		22.9		nC
Gate to Drain Charge		Q _{gd}			42.6		
Gate Charge Total		Q _g			86		
Gate Plateau Voltage		V _{plateau}			6.5		V
Reverse Diode Characteristics							
Drain-Source Diode Forward Voltage		V _{SD}	V _{GS} =0V, I _{SD} =18A		0.9	1.1	V
Reverse Recovery Time		t _{rr}	V _R =100V, I _F =18A dI _F /dt=100A/us		152		ns
Reverse Recovery Charge		Q _{rr}			0.89		uC
Peak Reverse Recovery Current		I _{rrm}			11.6		A

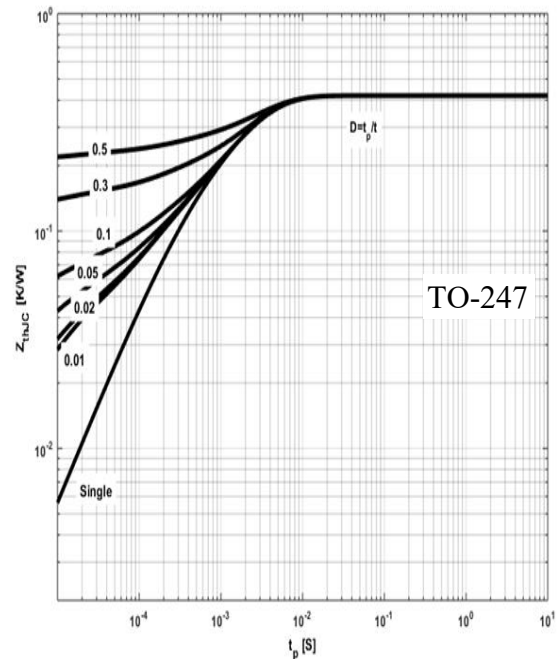
Note:

5. $C_{O(er)}$ is a fixed capacitance that gives the same stored energy as C_{OSS} while V_{DS} is rising from 0 to 480V

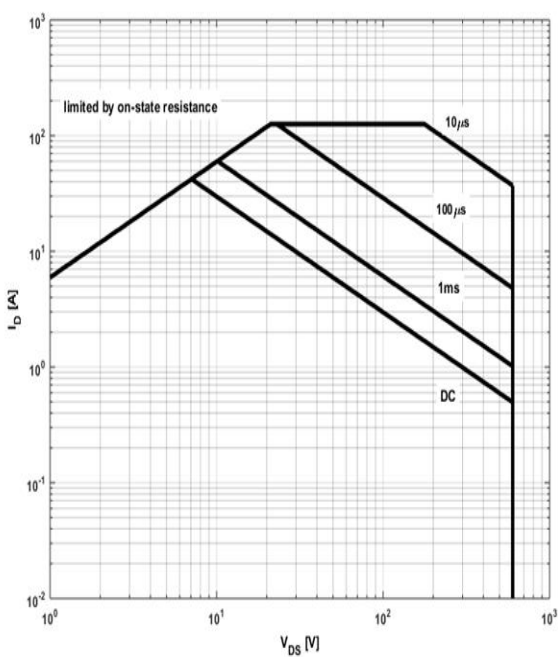
6. $C_{O(tr)}$ is a fixed capacitance that gives the same charging time as C_{OSS} while V_{DS} is rising from 0 to 480 V

Typical Performance Characteristics
Figure 3: Power Dissipation


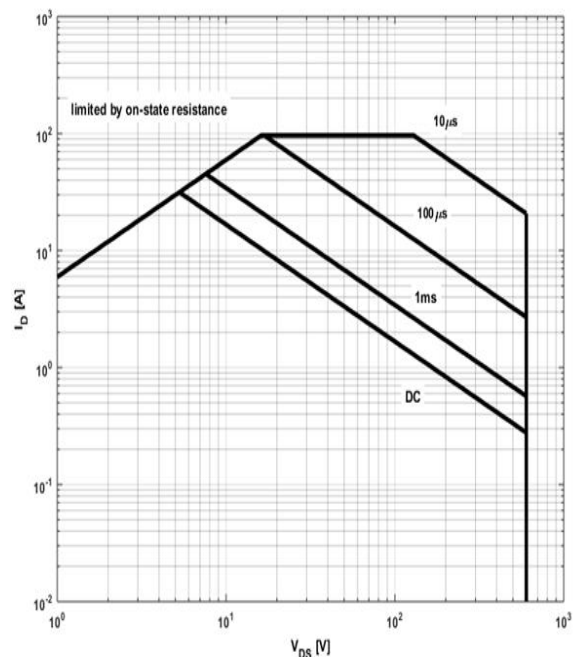
$$P_{\text{tot}} = f(T_c)$$

Figure 4: Max. Transient Thermal Impedance


$$Z_{\text{thJC}} = f(t_p); \text{ parameter: } D = t_p / T$$

Figure 5: Safe Operating Area


$$I_D = f(V_{DS}); T_c = 25^\circ\text{C}; V_{GS} > 7\text{V}; \text{ parameter } t_p$$

Figure 6: Safe Operating Area


$$I_D = f(V_{DS}); T_c = 80^\circ\text{C}; V_{GS} > 7\text{V}; \text{ parameter } t_p$$

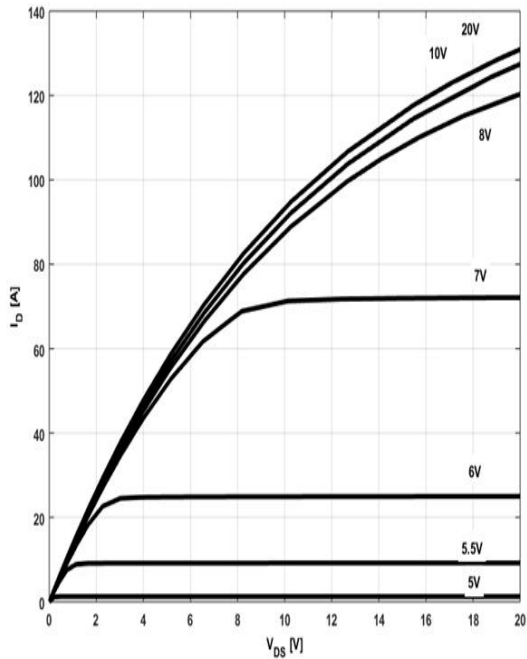
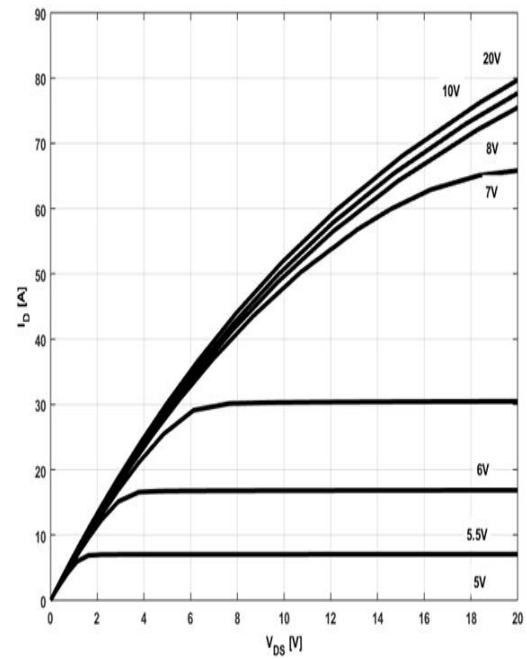
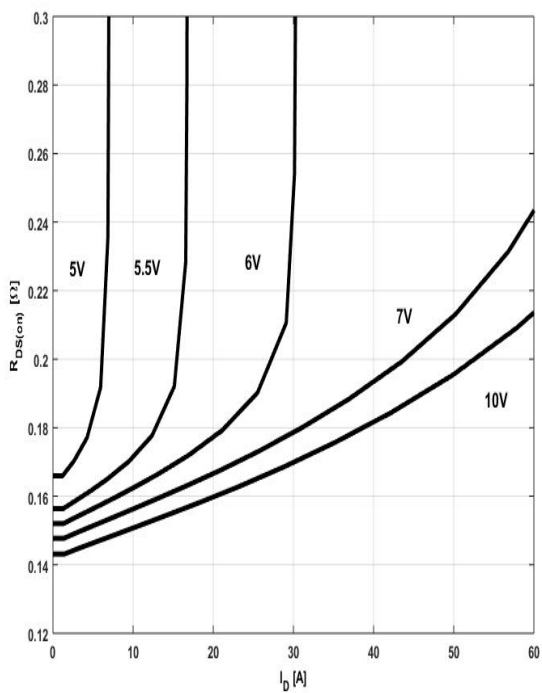
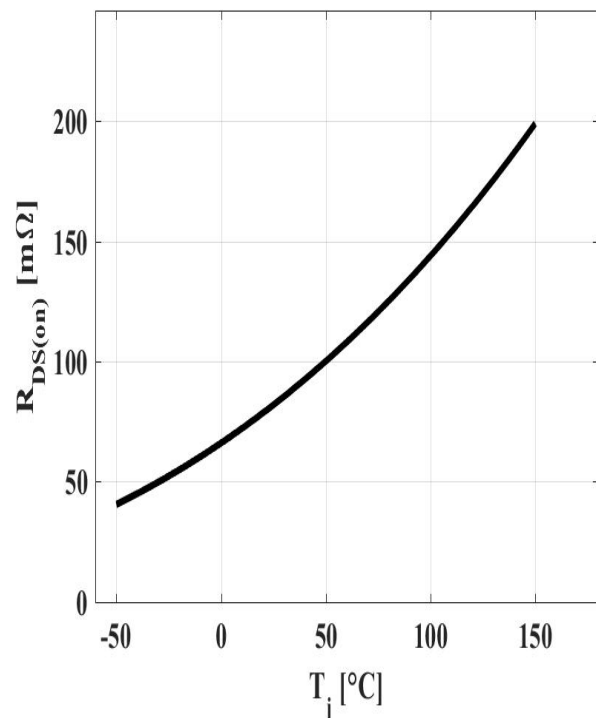
Figure 7: Typ. Output Characteristics

 $I_D = f(V_{DS}); T_j = 25^\circ\text{C}; \text{parameter: } V_{GS}$
Figure 8: Typ. Output Characteristics

 $I_D = f(V_{DS}); T_j = 125^\circ\text{C}; \text{parameter: } V_{GS}$
Figure 9: Typ. Drain-Source On-State Resistance

 $R_{DS(ON)} = f(I_D); T_j = 125^\circ\text{C}; \text{parameter: } V_{GS}$
Figure 10: Typ. Drain-Source On-State Resistance

 $R_{DS(ON)} = f(T_j); I_D = 18\text{A}; V_{GS} = 10\text{V}$

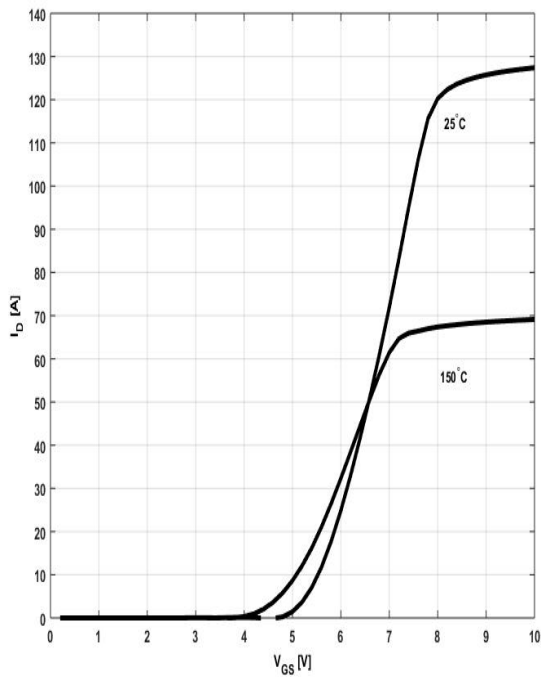
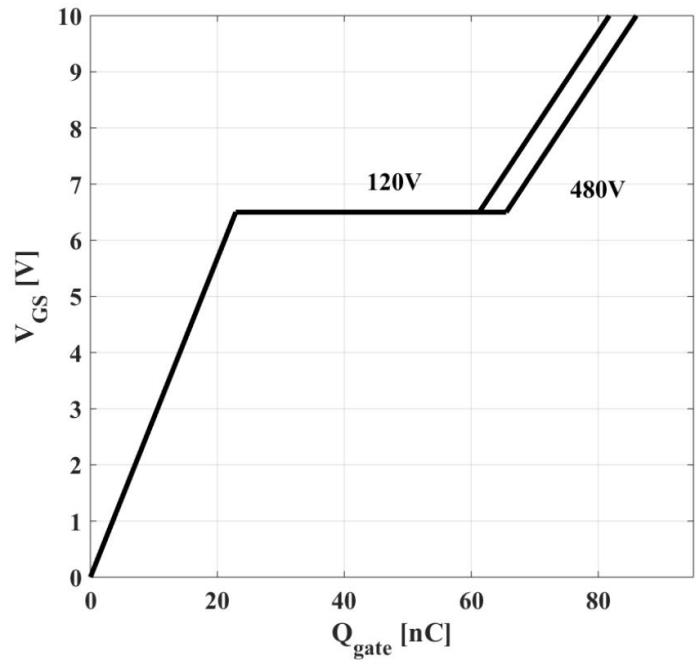
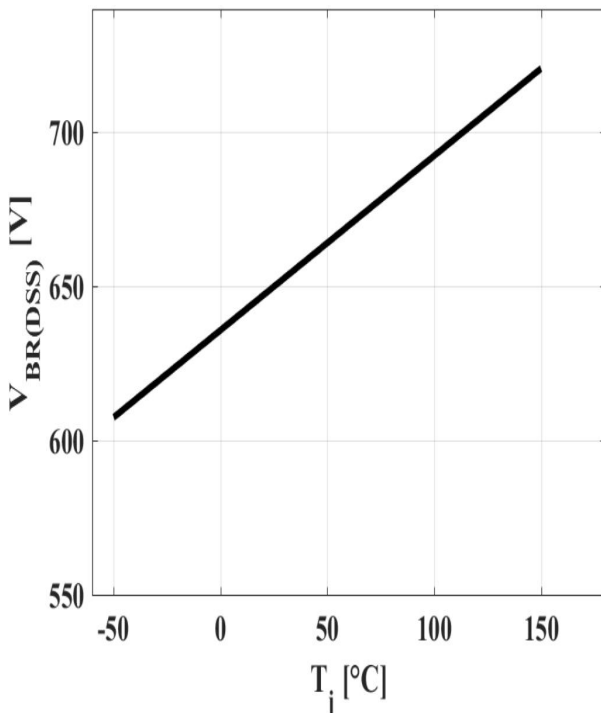
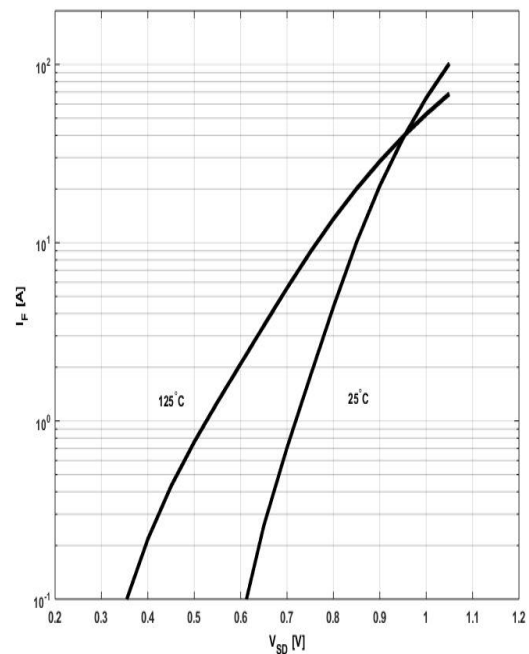
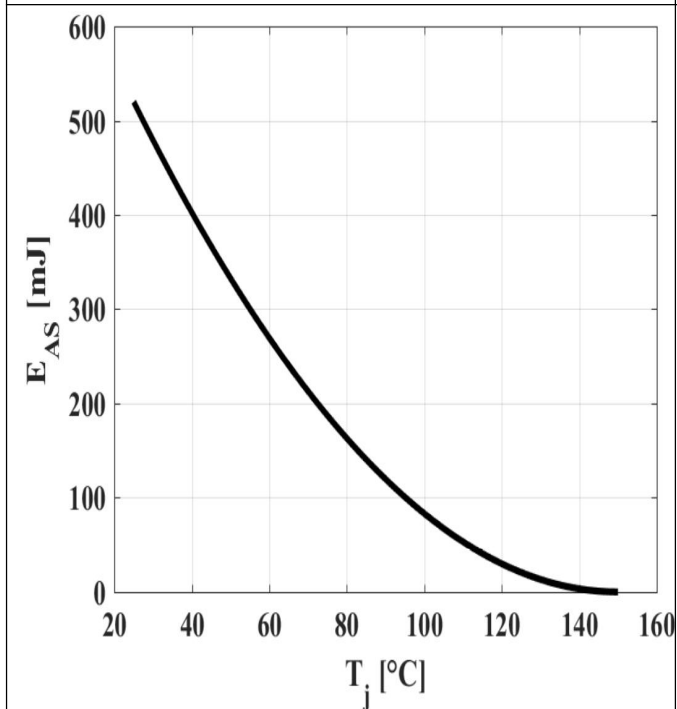
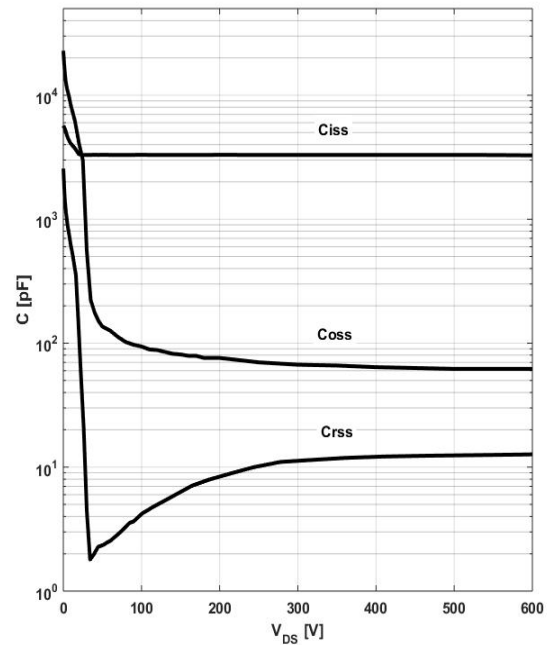
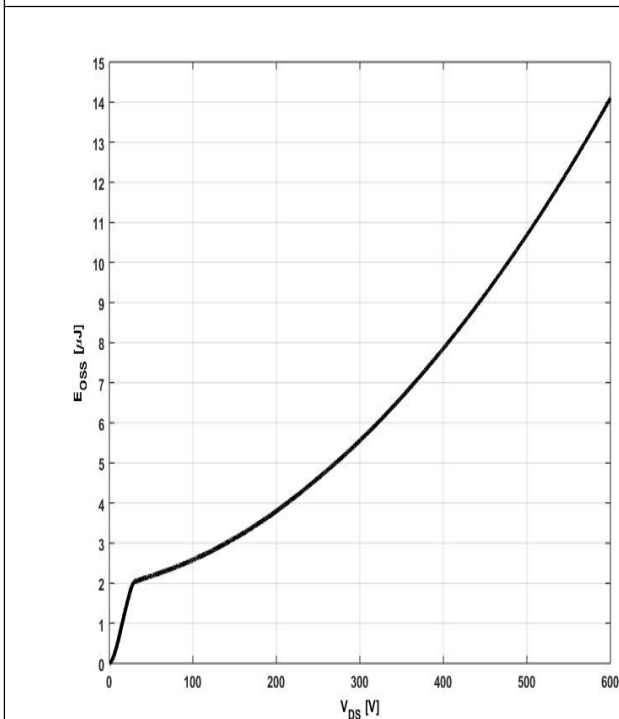
Figure 11: Typ. Transfer Characteristics

 $I_D = f(V_{GS}); V_{DS} = 20V$
Figure 12: Typ. Gate Charge

 $V_{GS} = f(Q_{gate}), I_D = 18A \text{ pulsed}$
Figure 13: Drain-Source Breakdown Voltage

 $V_{BR(DSS)} = f(T_j); I_D = 10mA$
Figure 14: Forward Characteristics of Reverse Diode

 $I_F = f(V_{SD}); \text{parameter: } T_j$

Figure 15: Avalanche Energy


$$E_{AS}=f(T_j); I_D=4.5A; V_{DD}=60V$$

Figure 16: Typ. Capacitances


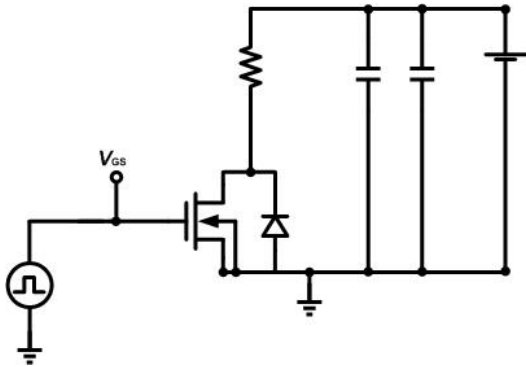
$$C=f(V_{DS}); V_{GS}=0; f=1MHz$$

Figure 17: Coss Stored Energy


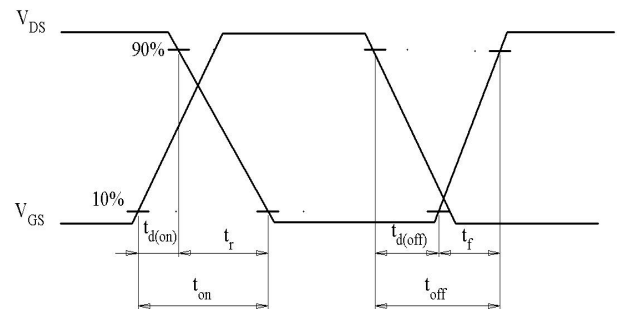
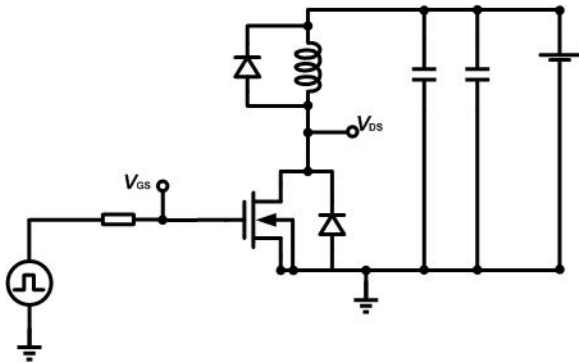
$$E_{OSS}=f(V_{DS})$$

Test Circuits

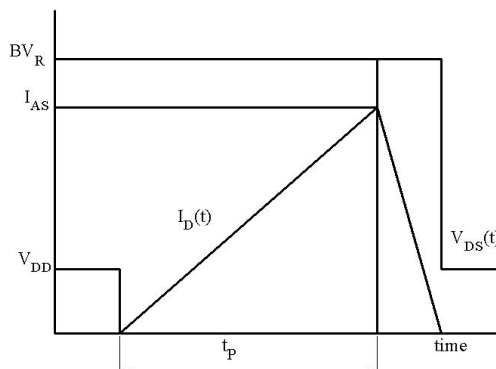
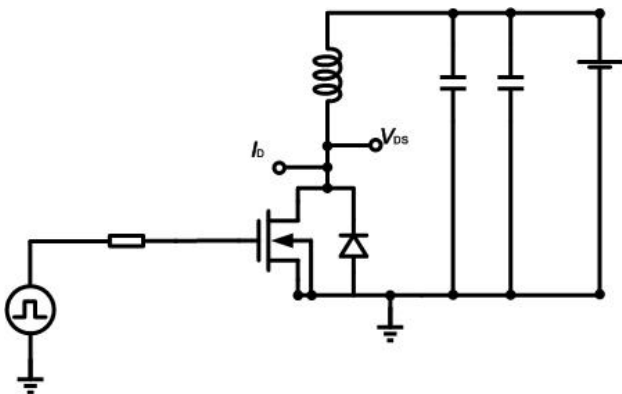
1. Gate Charge Test Circuit & Waveform



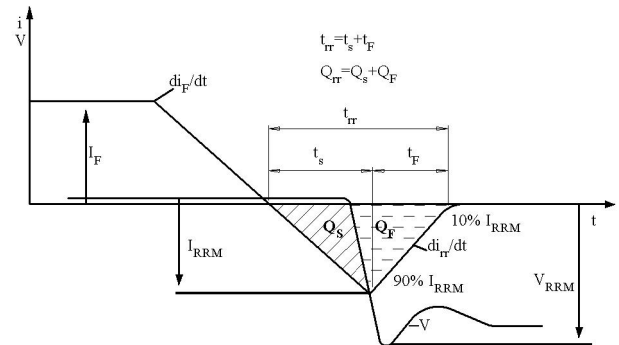
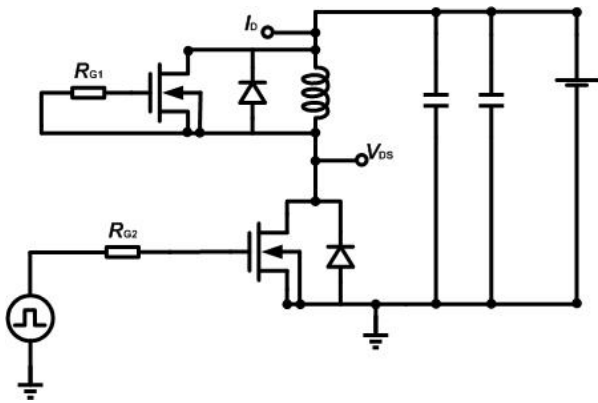
2. Switch Time Test Circuit

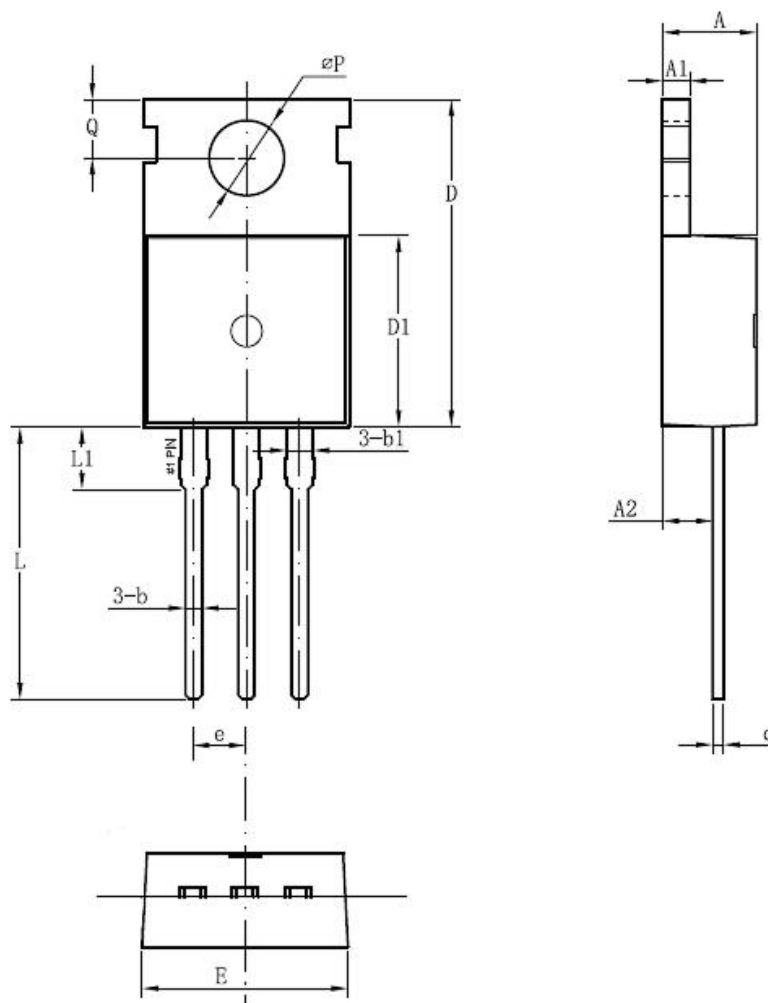


3. Unclaimed Inductive Switching Test Circuit & Waveforms

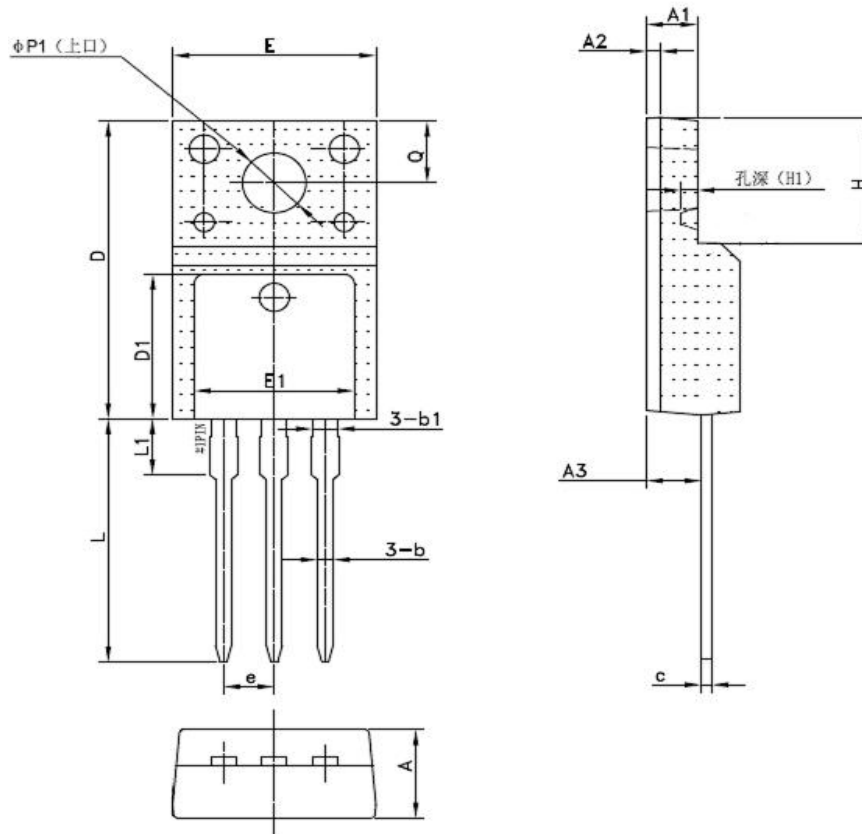


4. Test Circuit and Waveform for Diode Characteristics

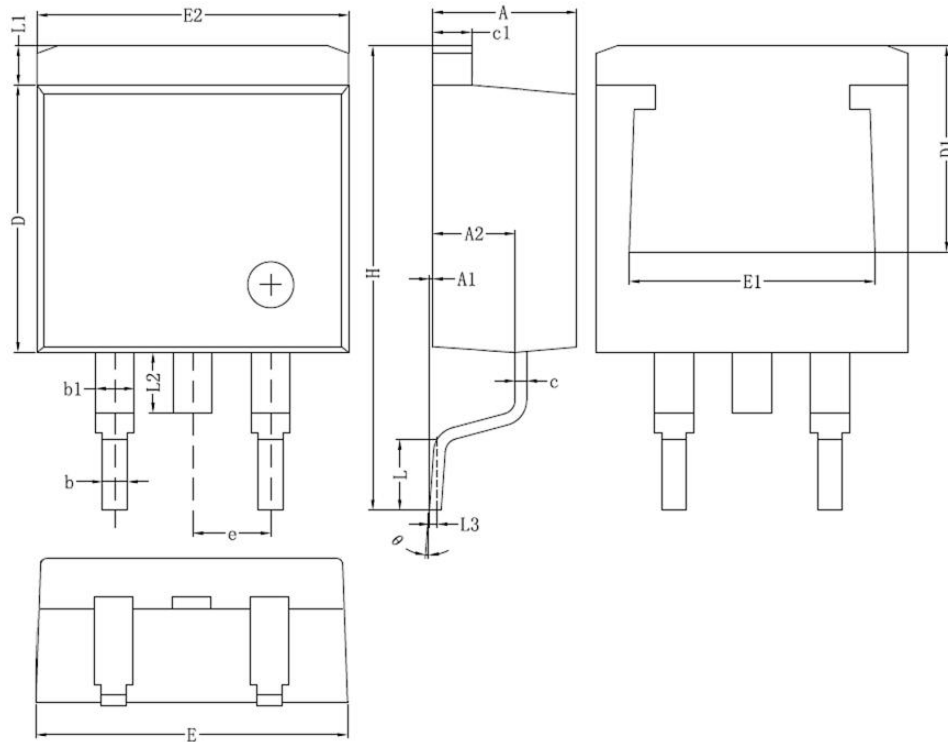


Mechanical Dimensions
TO-220C
Unit: mm


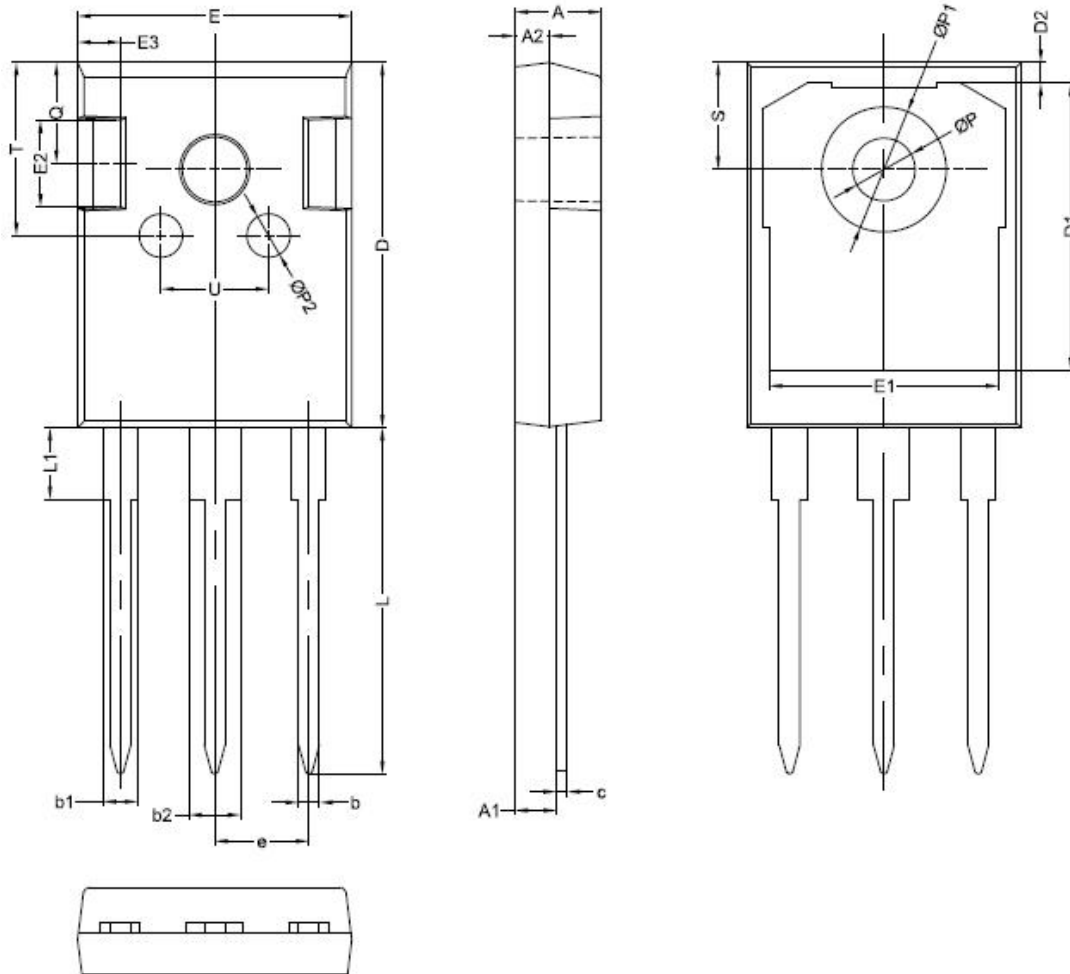
Symbol	Dimensions(mm)		
	Min.	Typ.	Max.
A	4.30	4.50	4.70
A1	1.20	1.30	1.40
A2	2.20	2.40	2.60
b	0.70	0.80	0.95
b1	-	1.27	-
c	0.40	0.50	0.65
D	15.20	15.70	16.20
D1	9.00	9.20	9.40
E	9.70	10.00	10.20
e	2.54(BSC)		
L	12.60	13.08	13.60
L1	-	3.00	-
ϕP	3.50	3.60	3.80
Q	2.60	2.80	3.00

Mechanical Dimensions(Continued)
TO-220F
Unit: mm


Symbol	Dimensions(mm)		
	Min.	Typ.	Max.
A	4.30	4.70	4.90
A1	2.34	2.54	2.90
A2	-	0.70	-
A3	2.56	2.76	2.96
b	0.55	-	0.95
b1	-	1.28	-
c	0.42	0.50	0.70
D	14.70	-	16.07
D1	-	7.70	-
E	9.96	10.16	10.36
E1	-	8.00	-
e	2.54(BSC)		
H	-	6.70	-
(H1)	-	(0.81)	-
L	12.48	12.98	13.50
L1	-	2.93	-
ΦP1	-	3.18	-
Q	2.90	3.30	3.50

Mechanical Dimensions (Continued)
TO-263-2
Unit: mm


Symbol	Dimensions(mm)		
	Min.	Typ.	Max.
A	4.30	4.60	4.85
A1	0.00	0.10	0.25
A2	2.59	2.69	2.89
b	0.70	0.81	0.96
b1	-	1.27	-
c	0.36	0.40	0.61
c1	1.15	1.27	1.40
D	8.55	-	9.40
D1	6.40	-	-
E	9.80	10.10	10.31
E1	7.60	-	-
E2	9.80	10.00	10.20
e	2.54(BSC)		
H	14.70	15.20	16.00
L	2.00	2.30	2.84
L1	1.00	1.27	1.40
L2	-	-	2.20
L3	-	0.25	-
θ	0°	-	8°

Mechanical Dimensions (Continued)
TO-247
Unit: mm


Symbol	Dimensions(mm)			Symbol	Dimensions(mm)		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.80	5.00	5.20	E2	-	5.00	-
A1	2.21	2.41	2.61	E3	-	2.50	-
A2	1.90	2.00	2.10	e	5.44(BSC)		
b	1.10	1.20	1.35	L	19.42	19.92	20.42
b1	-	2.00	-	L1	-	4.13	-
b2	-	3.00	-	P	3.50	3.60	3.70
c	0.55	0.60	0.75	P1	-	-	7.40
D	20.80	21.00	21.20	P2	-	2.50	-
D1	-	16.55	-	Q	-	5.80	-
D2	-	1.20	-	S	6.05	6.15	6.25
E	15.60	15.80	16.00	T	-	10.00	-
E1	-	13.30	-	U	-	6.20	-



Shenzhen Sanrise Technology Co., LTD

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